



**BRIGHTTEK**  
**BRIGHTTEK (EUROPE) LIMITED**

*Brighten Up The World With LED!*



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

## PRODUCT DATASHEET

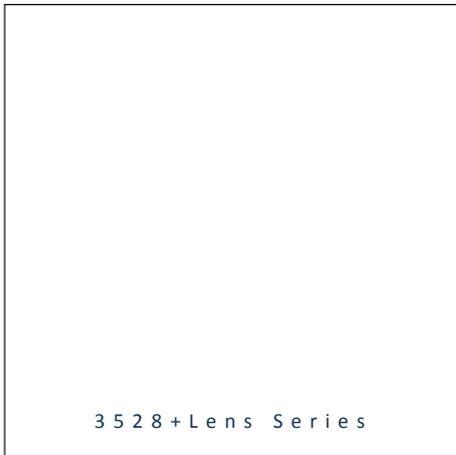


- ▶ PLCC4
- ▶ 3528+Lens Series
- ▶ Infrared (850nm)

NOF12S43



Release Date: 26 May 2015 Version: A1.2



3528+Lens Series

### 3528+Lens Series

**RoHS**  
Compliant



#### FEATURES:

- **Package:** PLCC4 White SMT Package with Lens
- **Forward Current:** 100mA
- **Forward Voltage (typ.):** 1.5V
- **Luminous Intensity (typ.):** 16 mW/sr @100mA
- **Colour:** Infrared
- **Wavelength:** 850nm
- **Viewing angle:** 30°
- **Materials:**
  - Die: AlGaAs/AlGaAs
  - Resin: Epoxy (Water Clear)
  - L/F Finish: Ag Plated
- **Operating Temperature:** -40~+80°C
- **Storage Temperature:** -40~+85°C
- **Soldering methods:** Reflow soldering
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 12mm tape with 2000pcs/reel, ø330mm (13")

#### APPLICATIONS:

- Security Device
- Sensor
- 3C Application

## CHARACTERISTICS:

### Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	$I_F$	100	mA
Peak Forward Current Duty 1/8@1KHz	$I_{FP}$	1000	mA
Reverse Current	$I_R$	10	$\mu$ A
Power Dissipation	$P_D$	180	mW
Operating Temperature	$T_{OPR}$	-40~+80	°C
Storage Temperature	$T_{STG}$	-40~+85	°C

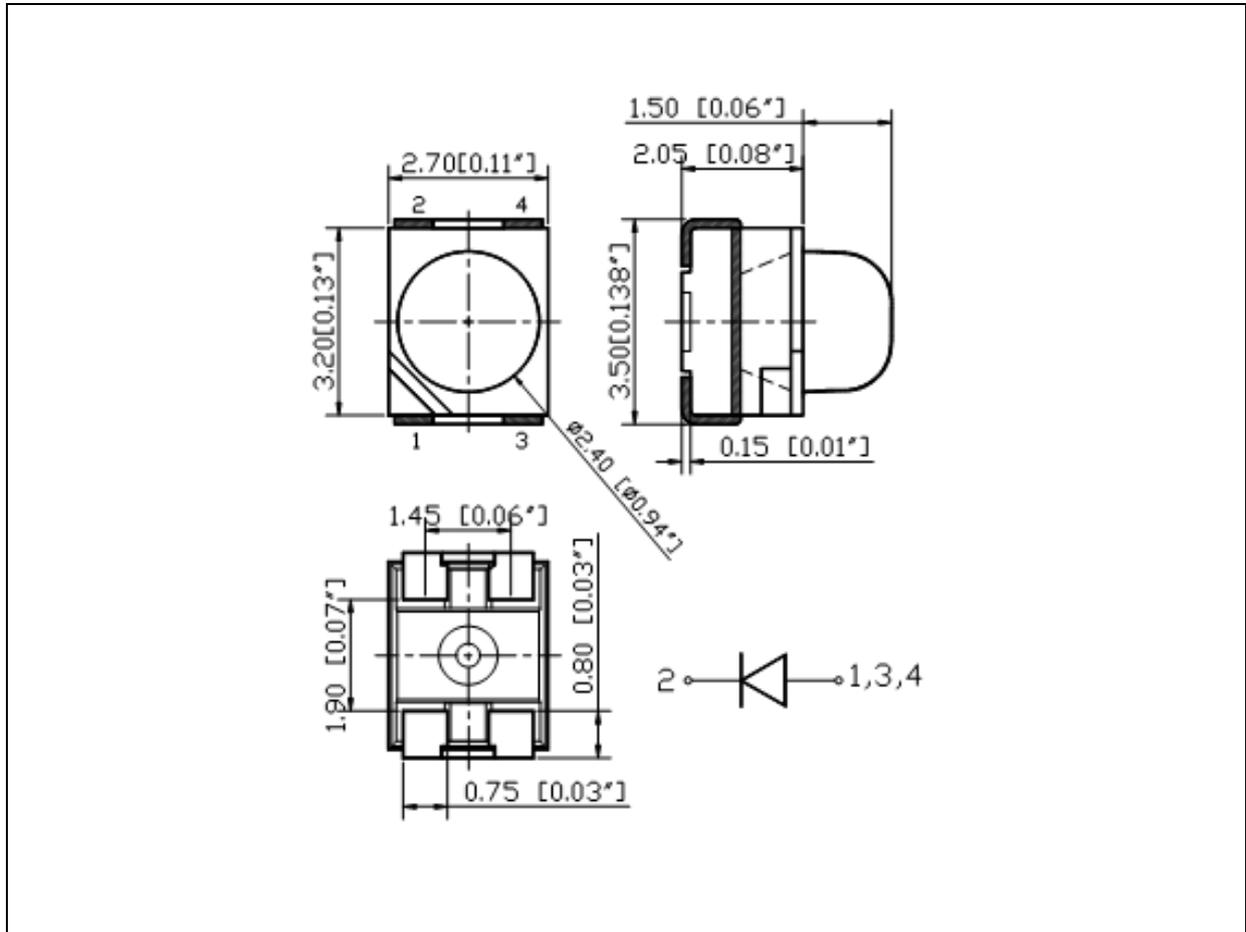
### Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	$V_F$	1.0	1.5	1.8	V	$I_F=100$ mA
Radiated Intensity	$I_V$	7.6	16.0	21.1	mW/sr	$I_F=100$ mA
Peak Wavelength	$\lambda_p$	840	850	860	nm	$I_F=100$ mA
Spectral Bandwidth	$\Delta\lambda$	---	50	---	nm	$I_F=100$ mA
Viewing Angle	$2\theta_{1/2}$	---	30	---	deg	$I_F=100$ mA

1. Luminous intensity ( $I_V$ )  $\pm 15\%$ , Forward Voltage ( $V_F$ )  $\pm 0.1V$ , Viewing angle( $2\theta_{1/2}$ )  $\pm 5\%$
2. IS standard testing

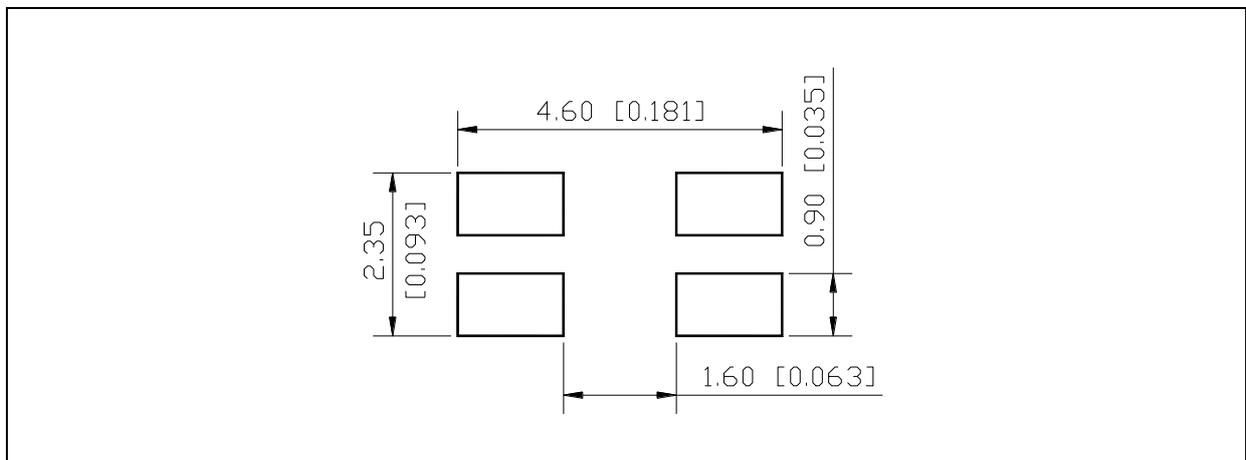
## OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.2$ mm, unless otherwise noted.

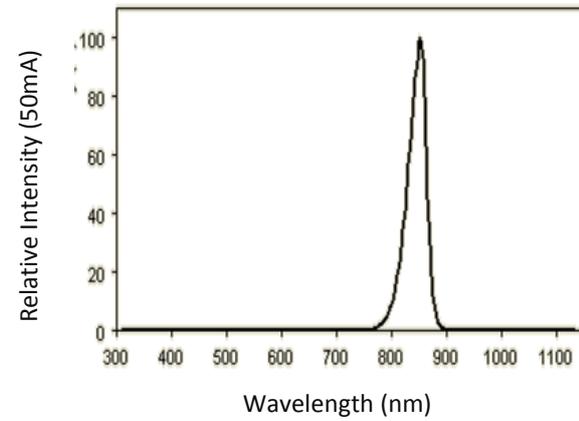
Recommended Soldering Pad Dimension:



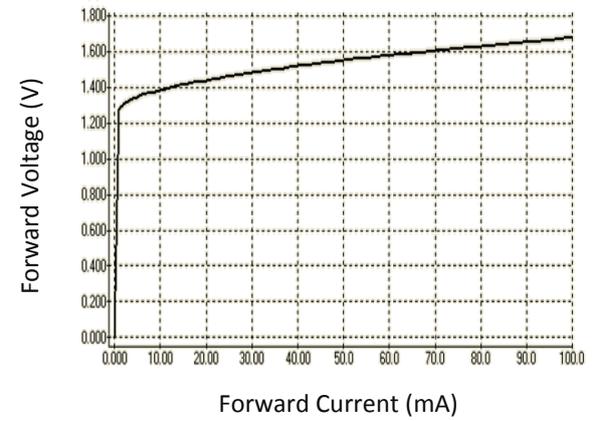
1. Dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.1$ mm with angle tolerance  $\pm 0.5^\circ$ .

**ELECTRO-OPTICAL CHARACTERISTICS:**

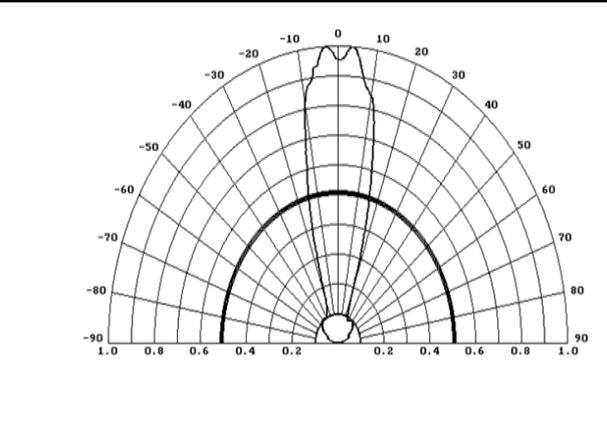
Relative Spectral Distribution



Forward Current v.s. Forward Voltage



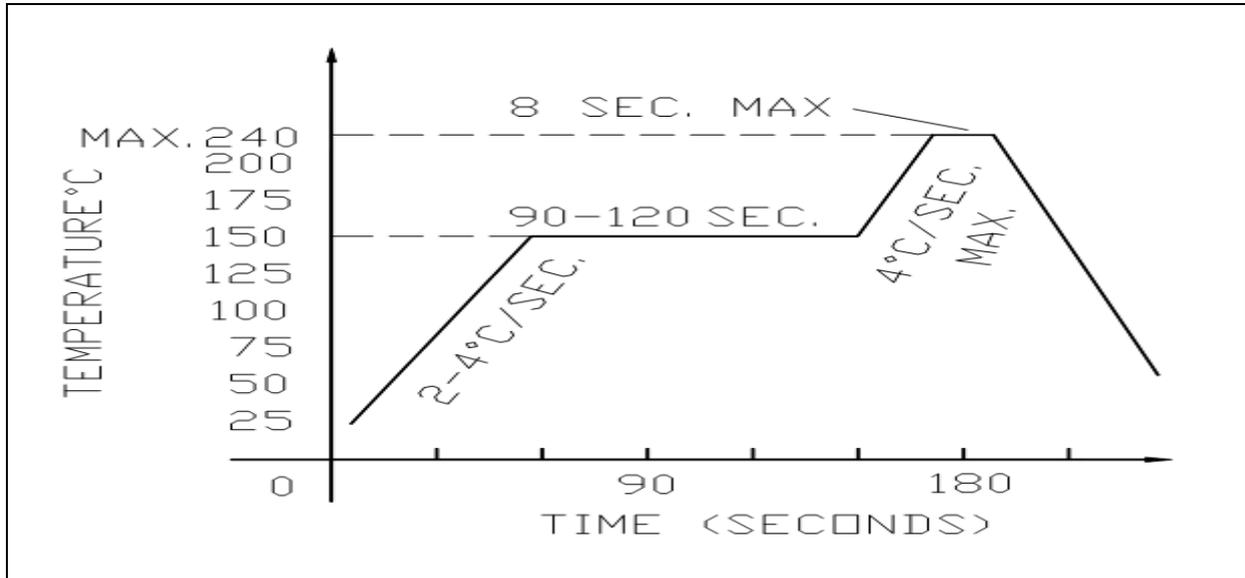
Directive Radiation



## RECOMMENDED SOLDERING PROFILE:

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Lead-free Solder:



Note:

1. Maximum soldering temperature is 240°C.
2. Maximum reflow soldering: 1 time.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.



## PRECAUTIONS OF USE:

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### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent and apply baking at 60°C±5°C for 15hrs before use.

### Baking:

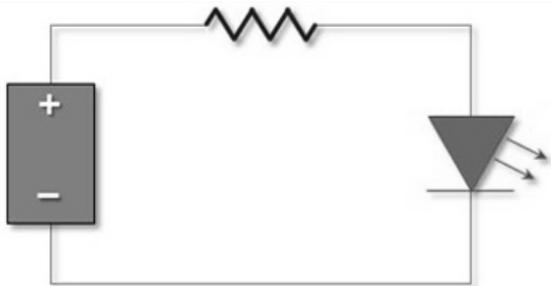
It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs.

The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### Testing Circuit:



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

**REVISION RECORD:**

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Version	Date	Summary of Revision
A1.0	28/10/2014	Datasheet set-up.
A1.1	26/05/2015	P4 wavelength graphic revision.